

Highlights

- Suitable for metals as well as hard materials, ceramics and workpieces with sharp edges
- Very good lifetime and economy compared to the competition
- Cleaner than lapping with grinding suspensions
- High flatness, surface quality and precise edges

Diamond grinding pad

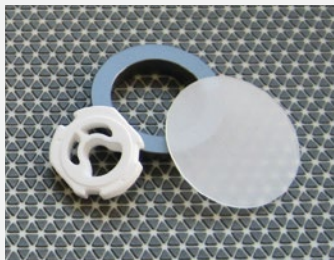
SQUADRO-M / SQUADRO-H

SQUADRO-M and SQUADRO-H are innovative diamond grinding pads that extend fine grinding to single-micron grit sizes. They replace conventional lapping processes, achieving superior results in terms of material removal rate, surface quality, workpiece geometry and lifetime. SQUADRO diamond grinding pads provide an easy, clean and efficient fine grinding process.

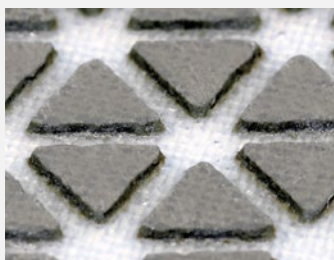
Typical applications

SQUADRO-M: Fine grinding of metals

SQUADRO-H: Fine grinding of hard materials, ceramics and sharp-edged workpieces



Diamond grinding pad SQUADRO.



Close-up on grinding pad SQUADRO.



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Product specifications

Abrasive layer thickness.....	0,4 mm
Bond type	SQUADRO-M: Resin, medium hard SQUADRO-H: Resin, hard
Carrier material	Textile base

Order information

Order code SQUADRO-H 30-OD300mm-PU1-PSA-D1

- ① Diamond size 3 µm, 6 µm, 15 µm, 30 µm, 60 µm
(125 µm only SQUADRO-H)
- ② Outer diameter 200 mm, 250 mm, 300 mm, 350 mm, 400 mm
- ③ Packing unit 1 piece / box
- ④ Backing / mounting PSA (self-adhesive)
SGM (metal plate)
MAG (magnetic foil)
- ⑤ Drawing index optional

Application recommendations

Dressing	Prior to the first use, the SQUADRO-M and SQUADRO-H pads have to be dressed and planarized with a dressing tool (e.g. Al ₂ O ₃ with grit 280 mesh (grit size 60 µm, 125 µm) or 400 mesh (grit size 3 µm, 6 µm, 15 µm, 30 µm)).
Cleaning	To ensure cutting efficiency of the bonding, the grinding pad has to be cleaned from abrasive debris regularly. Best suited for this are brass brushes for manual or machine use. Machine brushes can be ordered from Pureon as accessories.
Coolant	SQUADRO-LUB+ is recommended and a water-soluble cooling and lubricating fluid that ensures high and consistent material removal. DI-water is only partly suited. No dry running. Organic solvent and oil based lubricants may harm the pad and are therefore not recommended.

Grinding parameters

Grinding pressure	Recommended: 2 – 10 N/cm ² , max. 15 N/cm ²
Circumferential speed	Recommended: 5 m/s, max. 10 m/s

Contact

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